

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	53064	(pcb or board) and (via or hole\$1 or opening\$1 or aperture\$1 or recess\$2 or pore\$1) and (cut\$4) and (fill\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 18:59
L2	10408	1 and (pcb or board) near5 (via or hole\$1 or opening\$1 or aperture\$1 or recess\$2 or pore\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:00
L3	4223	2 and (fill\$3) near15 (via or hole\$1 or opening\$1 or aperture\$1 or recess\$2 or pore\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:01
L4	1155	3 and (cut\$4) near5 (via or hole\$1 or opening\$1 or aperture\$1 or recess\$2 or pore\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:01
L5	130	3 and (cut\$4) near5 (via or hole\$1 or opening\$1 or aperture\$1 or recess\$2 or pore\$1) near15 (metal or aluminum or copper)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:02
L6	54	5 and (fill\$3) near15 (dielectric or insulat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:03
L7	11	6 and (cut\$4) near3 (line\$1 or street\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:04
L8	6	6 and (cut\$4) near (line\$1 or street\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:53
L9	4	((cut\$4) near (line\$1 or street\$)) near10 (laser near ablation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:55

L10	13	((cut\$4) near (via or hole or opening)) near10 (laser near ablation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:59
L11	4	((cut\$4) near (recess\$2 or aperture)) near10 (laser near ablation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:57
L12	24	((cut\$4) near3 (via or hole or opening)) near10 (laser near ablation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:59
L13	22	12 and method	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:59
L14	0	12 and method with sunstrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 19:59
L15	12	12 and method with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:07
L16	208	(ink) near10 (insulat\$3) near10 (fill\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:08
L17	46	(ink) near10 (insulat\$3) near10 (fill\$3) near10 (via or hole or opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:15
L18	16	17 and (method with substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:14
L19	13	17 and (method with board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:11

L20	2	17 and (method with circuit near substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:14
L21	3	17 and (method with circuit near3 substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:15
L22	0	(ink) near10 (insulat\$3) near10 (fill\$3) near10 (via or hole or opening) with (cut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:16
L23	3	(ink) near10 (insulat\$3) near10 (fill\$3) near10 (via or hole or opening) same (cut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:16
L24	16	(ink) near10 (insulat\$3) near10 (fill\$3) near10 (via or hole or opening) and (cut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 20:16